

July 2nd, 2004, Friday			
Session No 6: Dispensing technology and Soldering			
Chair	Dr. Horation Quinones Asyntek, USA		
Co-Chair	Prof. X.M.Xie Shanghai Institute of Microsystem and Information Technology, China		
Venue	Room 2		
Time	No. of Paper	Title	Speaker
8.00-8.20	S6-0	New Dispensiing Technology	Horation Quinones, Asyntek, USA
8.20-8.40	S6-1	Experimental Study of Component Placement in Solder Paste	Martin Dahlberg Mydata automation AB, Göteborg, Sweden
8.40-9.00	S6-2	Analysis & Solution for the White-Residue after Soldering	Zhe Liu Shen Zhen ZTE Co. Ltd, Shen Zhen , Guangdong , P.R.C.
9.00-9.20	S6-3	Technology development and basic theory study of fluid dispensing —a review	Li Jianping College of mechanical and electrical engineering, Central South University, ChangSha , HuNan, China
9.20-9.40	S6-4	An experimental system for the mechanism research of contact fluid dispensing dot	Deng GuiLing College of mechanical and electrical engineering, Central South University, ChangSha , HuNan, China
10.00-10.30	Coffee Break and Exhibition		